
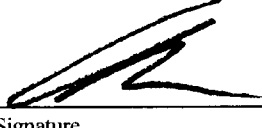


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10/240023

Express Mail Number: EL 500 576 091 US

<p>9-25-02</p> <p>RECORDATION FORM COVER 102 Rec'd PCT/PTO 25 SEP 2002</p> <p>PATENTS ONLY</p> <p>03-05-2003</p> <p>Attorney Docket Number 7419-0030</p>	
TO THE HONOR	TRADEMARKS
 <p>102380859</p> <p>Please record the attached original documents or copy thereof.</p>	
<p>1. Name of conveying party(ies):</p> <p>Tetsuji Tokiwa</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: <u>Asahi Kasei Kabushiki Kaisha</u></p> <p>Address: <u>2-6, Dojimahama 1-chome</u></p> <p><u>Kita-ku, Osaka-shi</u></p> <p><u>Osaka 530-8205</u></p> <p><u>JAPAN</u></p> <p>Country (if other than USA): <u>JAPAN</u></p>
<p>3. Nature of conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger</p> <p><input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name</p> <p><input type="checkbox"/> Other _____</p> <p>Execution Date: <u>September 13, 2002</u></p>	
<p>4. Application number(s) or patent number(s):</p> <p>If this document is being filed together with a new application, the execution date of the application is: <u>September 13, 2002</u></p> <p>A. Patent Application No.(s) <u>10240023</u> B. Patent No.(s) _____</p> <p style="text-align: center;">Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>PENNIE & EDMONDS LLP 1155 Avenue of Americas New York, N.Y. 10036-2711</p>	<p>6. Number of applications and patents involved: <u>1</u></p> <p>7. Total fee (37 CFR 3.41):.....\$ <u>40</u> Please charge to the deposit account listed in Section 8.</p> <p>8. Deposit account number: <u>16-1150</u></p>
<p>10/01/2002 LLANDGRA 00000130 161150 10240023</p> <p>03 FC 581 40.00 CH</p> <p>DO NOT USE THIS SPACE</p>	
<p>9. Statement and signature.</p> <p><i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i></p> <p>Charles E. Miller 24,576  September 25, 2002</p> <p>Name of Person Signing Reg. No. Signature Date</p> <p style="text-align: right;">Total number of pages including cover sheet: 2</p>	

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignment
Washington, D.C. 20231

PATENT
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ASSIGNMENT

WHEREAS, I, Tetsuji TOKIWAASSIGNOR, a citizen of Japan, residing at, Chiba, Japanam the inventor of the invention in FUNCTIONALIZED POLYPHENYLENE ETHER RESIN

for which I have executed an application for a Patent of the United States

☒ on even date herewith and/or which is identified by Pennie & Edmonds docket no. _____
☐ which was filed on _____, Serial No. _____

and WHEREAS, ASAHI KASEI KABUSHIKI KAISHA,whose address is 2-6, Dojimahama 1-chome, Kita-ku, Osaka-shi, Osaka 530-8205
Japan

ASSIGNEE, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof.

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States to issue any and all patents or other evidence or forms of industrial property protection on applications as aforesaid, to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set below my signature.

Tetsuji Tokiwa L.S.
[Name]

Signed and sworn to before me
this ____ day of _____, ~~1999~~
2002

September 13, 2002

[Date]

[Notary Public or U.S. Diplomatic or Consular Official]